

Electronic Patent Application Fee Transmittal

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| Application Number: | 10528153 | | | |
| Filing Date: | 19-Aug-2005 | | | |
| Title of Invention: | Method of adhesion of conductive materials, laminate, and adhesive composition | | | |
| First Named Inventor/Applicant Name: | Hiroyuki Sakamoto | | | |
| Filer: | Burton A. Amernick/Pam Rollins-Butler | | | |
| Attorney Docket Number: | 27604-00003US1 | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Miscellaneous: | | | | |
| Statutory disclaimer | 1814 | 1 | 140 | 140 |
| Total in USD (\$) | | | | 140 |